- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

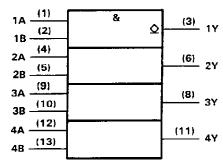
These devices contain four independent 2-input AND gates. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher VOH levels.

The SN5409, SN54LS09, and SN54S09 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN7409, SN74LS09, and SN74S09 are characterized for operation from 0°C to 70°C.

#### FUNCTION TABLE (each gate)

INP	UTS	QUTPUT				
Α	В	Y				
н	Н	Н				
L	Х	L				
Х	L	L				

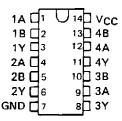
#### logic symbol



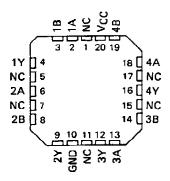
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN5409, SN54LS09, SN54S09... J OR W PACKAGE SN7409... N PACKAGE SN74LS09, SN74S09... D OR N PACKAGE (TOP VIEW)

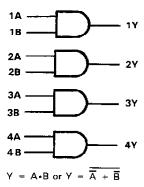


SN54LS09, SN54S09 . . . FK PACKAGE (TOP VIEW)

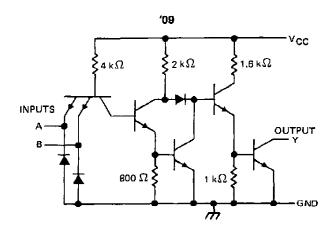


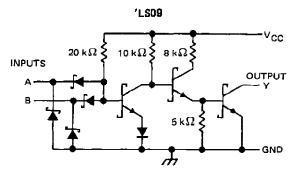
NC-No internal connection

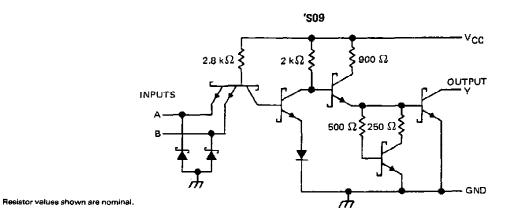
## logic diagram (positive logic)



#### schematics (each gate)







### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Input voltage: '09, 'S09		5.5 V
'LS09	· · · · · · · · · · · · · · · · · · ·	7 V
Operating free-air temperature range:	SN54'	–55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		–65°C to 150°C

NOTE 1; Voltage values are with respect to network ground terminal.

# SN5409, SN7409 QUADRUPLE 2 INPUT POSITIVE AND GATES WITH OPEN-COLLECTOR OUTPUTS

#### recommended operating conditions

	} :	SN5409			SN740	9	,,,,,,
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.8			8.0	٧
V <sub>OH</sub> High-level output voltage			5.5			5.5	٧
IOL Low-level output current			16			16	mΑ
TA Operating free-air temperature	- 55	-	125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN TYP\$ MAX	UNIT
VIK	VCC = MIN,	I <sub>I</sub> = - 12 mA	- 1,5	V
(он	V <sub>CC</sub> - MIN,	V <sub>1H</sub> = 2 V, V <sub>OH</sub> = 5,5 V	0.25	mA
VOL	V <sub>CC</sub> = MIN,	V <sub>IL</sub> = 0.8 V I <sub>OL</sub> = 16 mA	0.2 0.4	٧
lj.	VCC = MAX,	V <sub>j</sub> = 5.5 V	1	mΑ
Чн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.4 V	40	μД
liL.	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V	- 1.6	mA
ГССН	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V	11 21	mА
ICCL	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0 V	20 33	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	MAX	UNIT
<sup>t</sup> P <b>L</b> H			0.45.5		21	32	ns
t <b>P</b> HL	A or B	Υ	$H_L = 400 \Omega$ , $C_L = 15  pF$		16	24	пѕ

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

# SN54LS09, SN74LS09 QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS

### recommended operating conditions

	] ;	SN54LS	09	SN74LS09			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIII
VCC Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.7			8.0	V
VOH High-level output voltage			5.5			5.5	٧
IOL Low-level output current			4			8	mΑ
Тд Operating free-air temperature	- 55		125	0	•	70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

******		TEST CONDITIONS †			SN54LS	09	SN74LS09			
PARAMETER	1251 55/15/15/15			MIN	TYP‡	MAX	MIN	TYP\$	MAX	UNIT
VIK	V <sub>CC</sub> = MIN,	lı = — 18 mA				- 1.5			- 1.5	V
юн	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	V <sub>OH</sub> = 5.5 V			0.1			0.1	mΑ
	V <sub>CC</sub> = MIN,	V <sub>IL</sub> = MAX,	IOL = 4 mA		0.25	0.4		0.25	0.4	v
VOL	VCC = MIN,	VIL = MAX,	I <sub>OL</sub> = 8 mA				· · · · · · · · · · · · · · · · · · ·	0.35	0.5	\ \ \
11	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 7 V				0.1			0.1	mA
ЧН	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	μΑ
IIL.	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V	· · · · · · · · · · · · · · · · · · ·			- 0.4	***		- 0.4	mA
Іссн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V			2.4	4.8		2.4	4.8	mA
<sup> </sup> CCL	V <sub>CC</sub> = MAX,	V  = 0 V			4,4	8.8		4.4	8.8	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO {QUTPUT}	TEST CON	TEST CONDITIONS		TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	v	$R_1 = 2 k\Omega$ ,	C <sub>f</sub> = 15 pF		20	35	ns
₹PHL	7, 5, 5	,	11[ - 2 838,	OE - 19 bi		17	35	กร

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

<sup>‡</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25°C.

# SN54S09, SN74S09 QUADRUPLE 2-INPUT POSITIVE-AND GATES WITH OPEN-COLLECTOR OUTPUTS

#### recommended operating conditions

		SN54S0	9		SN74S0		UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	ON 1
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>1H</sub> High-level input voltage	2			2			٧
V <sub>IL</sub> Low-level input voltage			0.8			0.8	v
VOH High-level output voltage			5.5	_		5.5	٧
IOL Low-level output current			20			20	mA
TA Operating free-air temperature	- 55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	MIN TYP# MAX	TINU
ViK	V <sub>CC</sub> = MIN,	i <sub>1</sub> = - 18 mA	-1.2	V
ГОН	VCC = MIN,	V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 5.5 V	0.25	mA
Vol	V <sub>CC</sub> = MIN,	V <sub>IL</sub> = 0.8 V, I <sub>OL</sub> = 20 mA	0.5	V
lj.	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 5.5 V	1	mA
<sup>1</sup> ін	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2,7 V	50	μА
li L	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.5 V	-2	mA
1 <sub>ССН</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V	18 32	mA
ICCL	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0 V	32 57	mΑ

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TYP	MAX	UNIT
<sup>‡</sup> PLH	A or B		R <sub>L</sub> = 280 Ω,	C <sub>I</sub> = 15 pF	6.5	10	ns
tPHL.		Y		c[ - 15 pr	6.5	10	ns
tPLH				0 .50 .5	9		ns
<sup>t</sup> PHL			RL = 280 Ω, —	C <sub>L</sub> = 50 pF	9		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

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## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
80019012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8001901CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8001901CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8001901DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
8001901DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7409N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7409N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS09J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS09N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS09N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





6-Dec-2006

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74S09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S09NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S09FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S09J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S09W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: .v. ... a new design.



#### PACKAGE OPTION ADDENDUM

6-Dec-2006

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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